

ABSTRACT

In a ceramic packaging method employing a flip-chip bonding, a gold bump is formed on a chip bond pad in a wafer and the wafer is divided into a plurality of chips by a die sawing. A Cu pattern and the gold bump are aligned on a ceramic package, thereby adhering a bottom chip to the ceramic package through the Cu pattern and the gold bump and a top chip is adhered to the bottom chip by using an adhesive, thereby forming a bottom/top chip structure of the bottom and top chip. The chip bond pad is electrically connected to the bottom chip and the top chip by interconnecting the bottom and the top chips and interconnected portions of the bottom and the top chips are encapsulated.